

# ISL9V5045S3S / ISL9V5045S3 EcoSPARK® N-Channel Ignition IGBT

500mJ, 450V

## Features

- SCIS Energy = 500mJ at  $T_J = 25^\circ\text{C}$
- Logic Level Gate Drive

## Applications

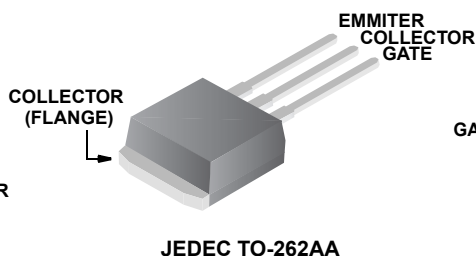
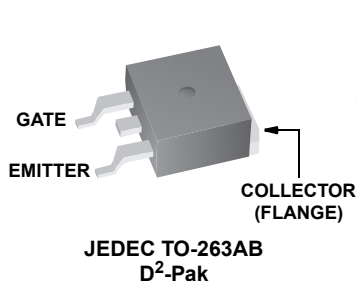
- Automotive Ignition Coil Driver Circuits
- Coil - On Plug Applications

## General Description

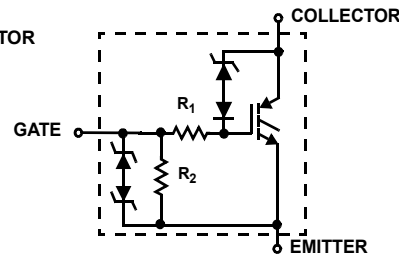
The ISL9V5045S3S and ISL9V5045S3 are next generation ignition IGBTs that offer outstanding SCIS capability in the industry standard D<sup>2</sup>-Pak (TO-263) plastic package. This device is intended for use in automotive ignition circuits, specifically as a coil drivers. Internal diodes provide voltage clamping without the need for external components.

**EcoSPARK®** devices can be custom made to specific clamp voltages. Contact your nearest Fairchild sales office for more information.

## Package



## Symbol



ISL9V5045S3S / ISL9V5045S3 N-Channel Ignition IGBT

**Device Maximum Ratings**  $T_A = 25^\circ\text{C}$  unless otherwise noted

Symbol	Parameter	Ratings	Units
$BV_{CER}$	Collector to Emitter Breakdown Voltage ( $I_C = 1\text{ mA}$ )	480	V
$BV_{ECS}$	Emitter to Collector Voltage - Reverse Battery Condition ( $I_C = 10\text{ mA}$ )	24	V
$E_{SCIS25}$	At Starting $T_J = 25^\circ\text{C}$ , $I_{SCIS} = 39.2\text{ A}$ , $L = 650\text{ }\mu\text{Hy}$	500	mJ
$E_{SCIS150}$	At Starting $T_J = 150^\circ\text{C}$ , $I_{SCIS} = 31.1\text{ A}$ , $L = 650\text{ }\mu\text{Hy}$	315	mJ
$I_{C25}$	Collector Current Continuous, At $T_C = 25^\circ\text{C}$ , See Fig 9	51	A
$I_{C110}$	Collector Current Continuous, At $T_C = 110^\circ\text{C}$ , See Fig 9	43	A
$V_{GEM}$	Gate to Emitter Voltage Continuous	$\pm 10$	V
$P_D$	Power Dissipation Total $T_C = 25^\circ\text{C}$	300	W
	Power Dissipation Derating $T_C > 25^\circ\text{C}$	2	$\text{W}/^\circ\text{C}$
$T_J$	Operating Junction Temperature Range	-40 to 175	$^\circ\text{C}$
$T_{STG}$	Storage Junction Temperature Range	-40 to 175	$^\circ\text{C}$
$T_L$	Max Lead Temp for Soldering (Leads at 1.6mm from Case for 10s)	300	$^\circ\text{C}$
$T_{pkg}$	Max Lead Temp for Soldering (Package Body for 10s)	260	$^\circ\text{C}$
ESD	Electrostatic Discharge Voltage at 100pF, 1500 $\Omega$	4	kV

**Package Marking and Ordering Information**

Device Marking	Device	Package	Reel Size	Tape Width	Quantity
V5045S	ISL9V5045S3ST	TO-263AB	330mm	24mm	800
V5045S	ISL9V5045S3	TO-262AA	Tube	N/A	50
V5045S	ISL9V5045S3S	TO-263AB	Tube	N/A	50

**Electrical Characteristics**  $T_A = 25^\circ\text{C}$  unless otherwise noted

Symbol	Parameter	Test Conditions	Min	Typ	Max	Units
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**Off State Characteristics**

BV <sub>CER</sub>	Collector to Emitter Breakdown Voltage	I <sub>C</sub> = 2mA, V <sub>GE</sub> = 0, R <sub>G</sub> = 1KΩ, See Fig. 15 T <sub>J</sub> = -40 to 150°C		420	450	480	V
BV <sub>CES</sub>	Collector to Emitter Breakdown Voltage	I <sub>C</sub> = 10mA, V <sub>GE</sub> = 0, R <sub>G</sub> = 0, See Fig. 15 T <sub>J</sub> = -40 to 150°C		445	475	505	V
BV <sub>ECS</sub>	Emitter to Collector Breakdown Voltage	I <sub>C</sub> = -75mA, V <sub>GE</sub> = 0V, T <sub>C</sub> = 25°C		30	-	-	V
BV <sub>GES</sub>	Gate to Emitter Breakdown Voltage	I <sub>GES</sub> = ± 2mA		±12	±14	-	V
I <sub>CER</sub>	Collector to Emitter Leakage Current	V <sub>CER</sub> = 320V, R <sub>G</sub> = 1KΩ, See Fig. 11	T <sub>C</sub> = 25°C	-	-	25	μA
			T <sub>C</sub> = 150°C	-	-	1	mA
I <sub>ECS</sub>	Emitter to Collector Leakage Current	V <sub>EC</sub> = 24V, See Fig. 11	T <sub>C</sub> = 25°C	-	-	1	mA
			T <sub>C</sub> = 150°C	-	-	40	mA
R <sub>1</sub>	Series Gate Resistance			-	100	-	Ω
R <sub>2</sub>	Gate to Emitter Resistance			10K	-	30K	Ω

**On State Characteristics**

$V_{CE(SAT)}$	Collector to Emitter Saturation Voltage	$I_C = 10\text{ A}$ , $V_{GE} = 4.0\text{ V}$	$T_C = 25^\circ\text{C}$ , See Fig. 4	-	1.25	1.60	V
$V_{CE(SAT)}$	Collector to Emitter Saturation Voltage	$I_C = 15\text{ A}$ , $V_{GE} = 4.5\text{ V}$	$T_C = 150^\circ\text{C}$	-	1.47	1.80	V

**Dynamic Characteristics**

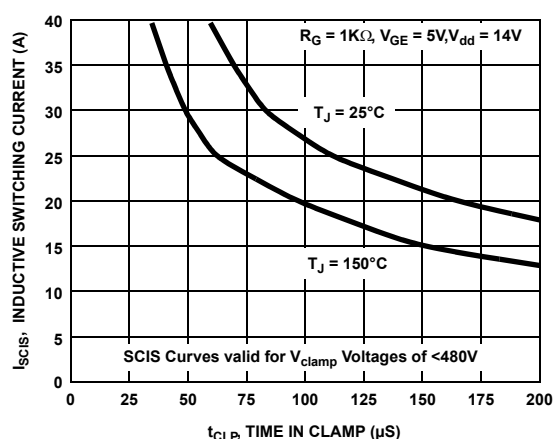
$Q_{G(ON)}$	Gate Charge	$I_C = 10A$ , $V_{CE} = 12V$ , $V_{GE} = 5V$ , See Fig. 14	-	32	-	nC
$V_{GE(TH)}$	Gate to Emitter Threshold Voltage	$I_C = 1.0mA$ , $V_{CE} = V_{GE}$ , See Fig. 10	$T_C = 25^\circ C$ $T_C = 150^\circ C$	1.3 0.75	- -	2.2 1.8 V V
$V_{GEP}$	Gate to Emitter Plateau Voltage	$I_C = 10A$ , $V_{CE} = 12V$	-	3.0	-	V

**Switching Characteristics**

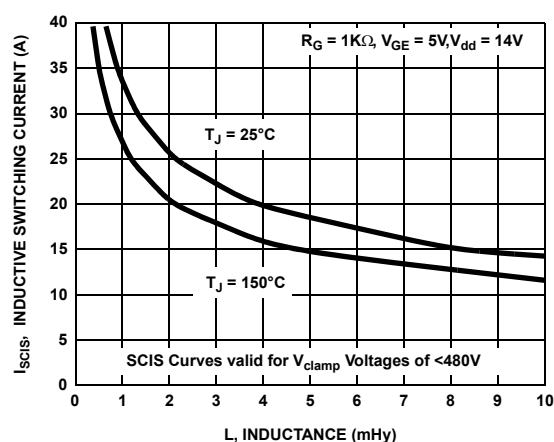
$t_{d(ON)R}$	Current Turn-On Delay Time-Resistive	$V_{CE} = 14V$ , $R_L = 1\Omega$ , $V_{GE} = 5V$ , $R_G = 1K\Omega$ $T_J = 25^\circ C$ , See Fig. 12	-	0.7	4	$\mu s$
$t_{rR}$	Current Rise Time-Resistive		-	2.1	7	$\mu s$
$t_{d(OFF)L}$	Current Turn-Off Delay Time-Inductive	$V_{CE} = 300V$ , $L = 2mH$ , $V_{GE} = 5V$ , $R_G = 1K\Omega$ $T_J = 25^\circ C$ , See Fig. 12	-	10.8	15	$\mu s$
$t_{fL}$	Current Fall Time-Inductive		-	2.8	15	$\mu s$
SCIS	Self Clamped Inductive Switching	$T_J = 25^\circ C$ , $L = 650 \mu H$ , $R_G = 1K\Omega$ , $V_{GE} = 5V$ , See Fig. 1 & 2	-	-	500	mJ

**Thermal Characteristics**

$R_{\theta JC}$	Thermal Resistance Junction-Case	TO-263, TO-262	-	-	0.5	$^\circ C/W$
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**Typical Characteristics**

**Figure 1. Self Clamped Inductive Switching Current vs Time in Clamp**



**Figure 2. Self Clamped Inductive Switching Current vs Inductance**

# Typical Characteristics (Continued)

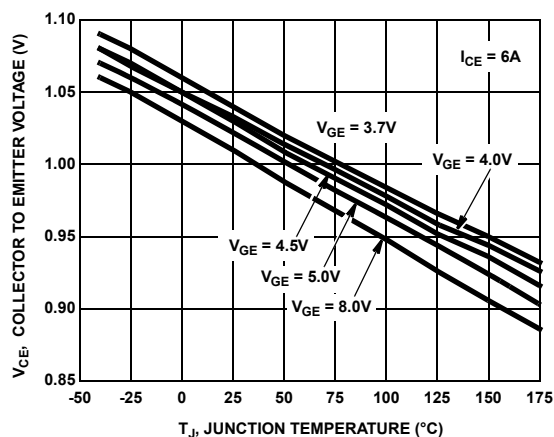


Figure 3. Collector to Emitter On-State Voltage vs Junction Temperature

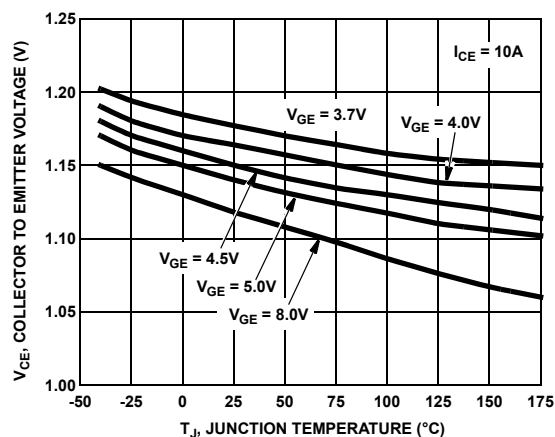


Figure 4. Collector to Emitter On-State Voltage vs Junction Temperature

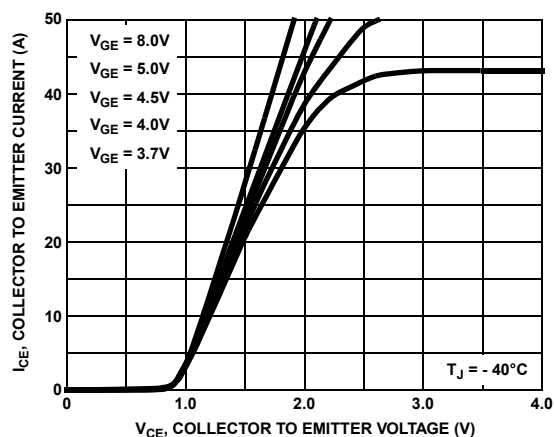


Figure 5. Collector Current vs Collector to Emitter On-State Voltage

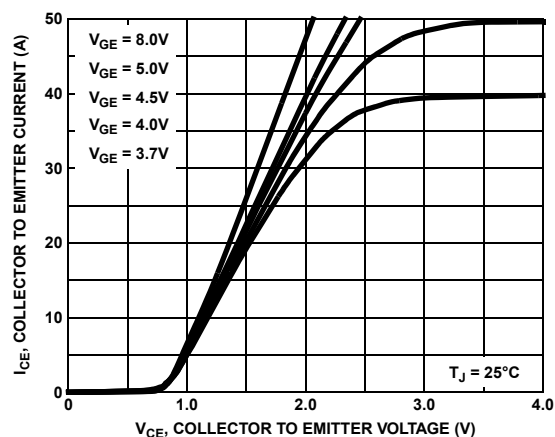


Figure 6. Collector Current vs Collector to Emitter On-State Voltage

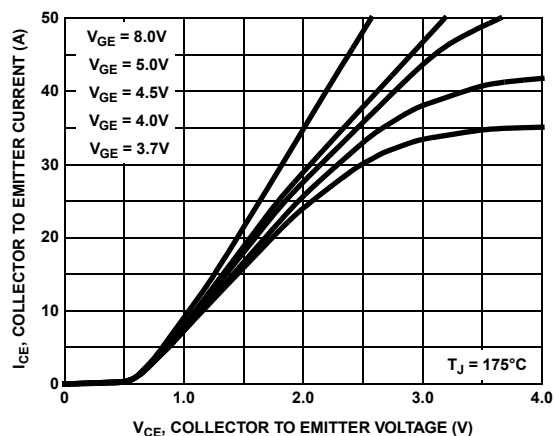


Figure 7. Collector to Emitter On-State Voltage vs Collector Current

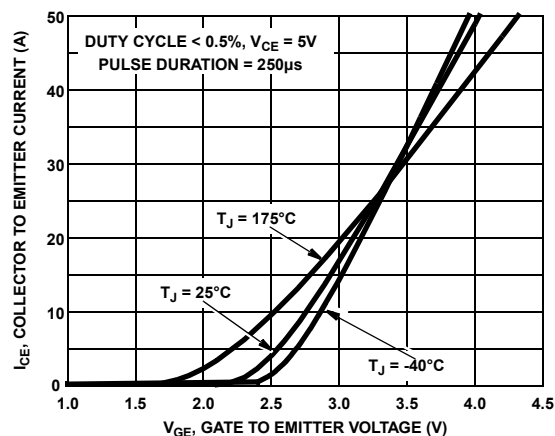
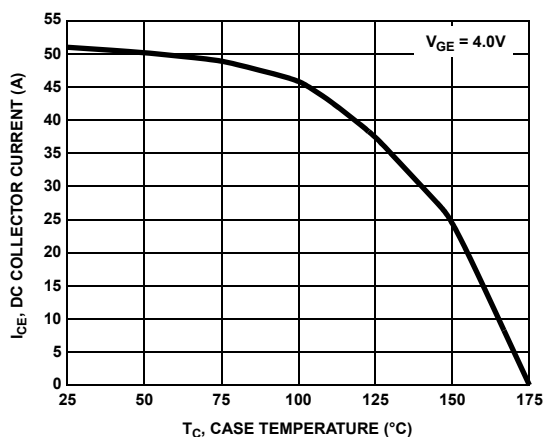
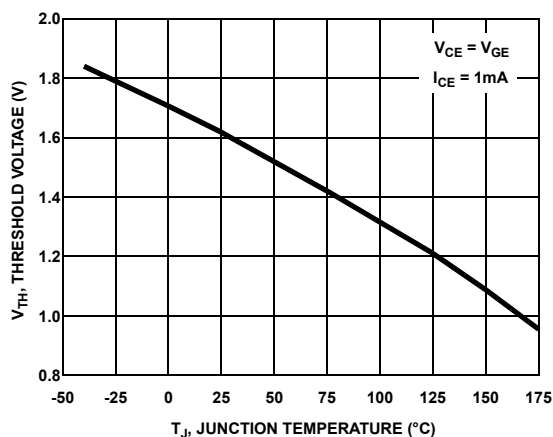


Figure 8. Transfer Characteristics

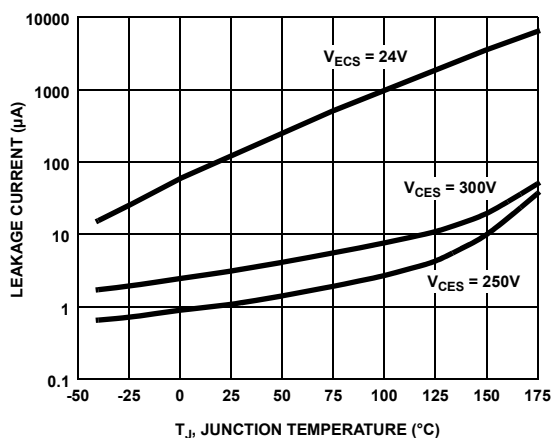
# Typical Characteristics (Continued)



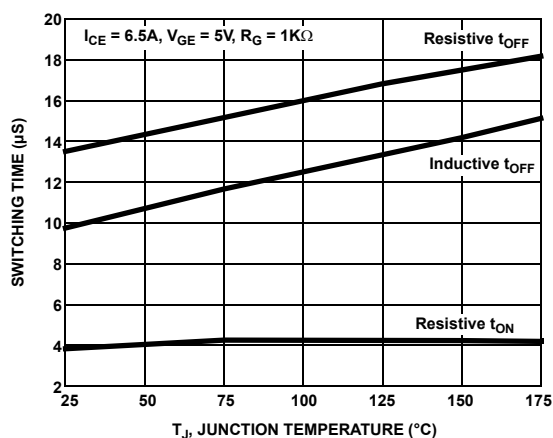
**Figure 9. DC Collector Current vs Case Temperature**



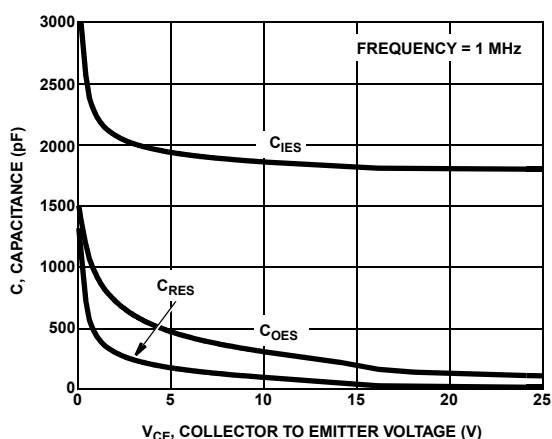
**Figure 10. Threshold Voltage vs Junction Temperature**



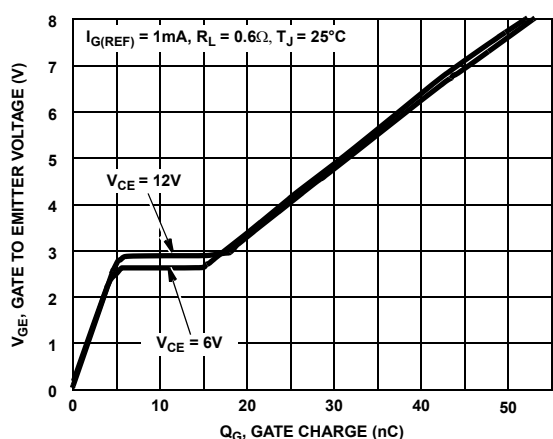
**Figure 11. Leakage Current vs Junction Temperature**



**Figure 12. Switching Time vs Junction Temperature**



**Figure 13. Capacitance vs Collector to Emitter Voltage**



**Figure 14. Gate Charge**

## Typical Characteristics (Continued)

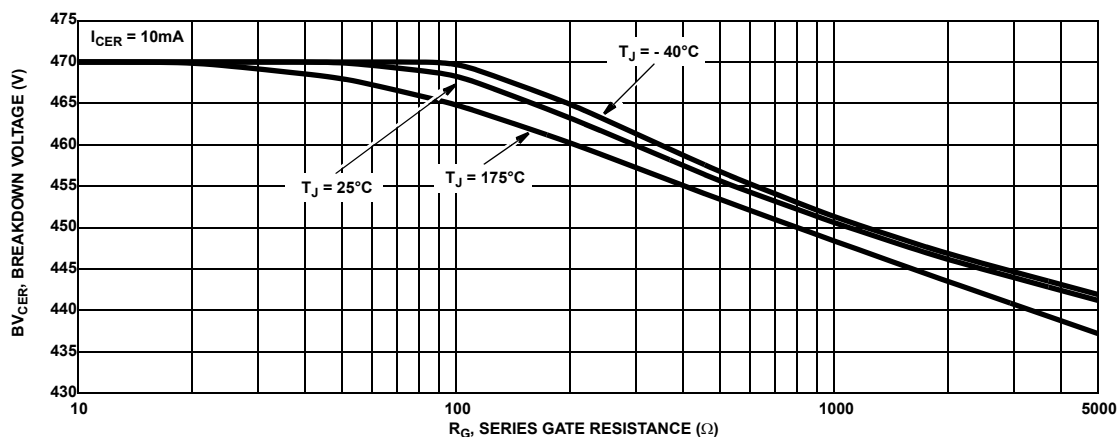


Figure 15. Breakdown Voltage vs Series Gate Resistance

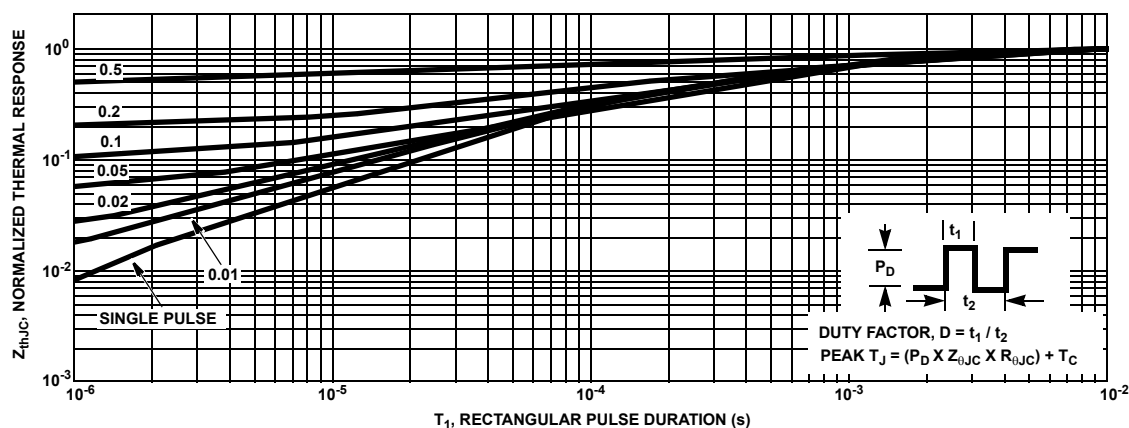


Figure 16. IGBT Normalized Transient Thermal Impedance, Junction to Case

## Test Circuits and Waveforms

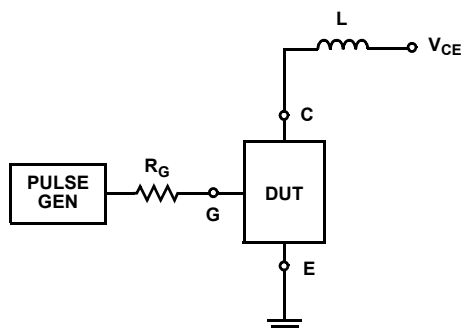


Figure 17. Inductive Switching Test Circuit

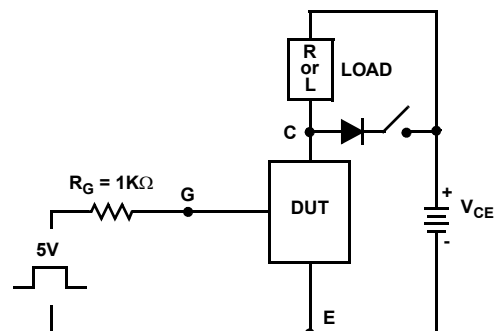


Figure 18.  $t_{ON}$  and  $t_{OFF}$  Switching Test Circuit

# Test Circuits and Waveforms (Continued)

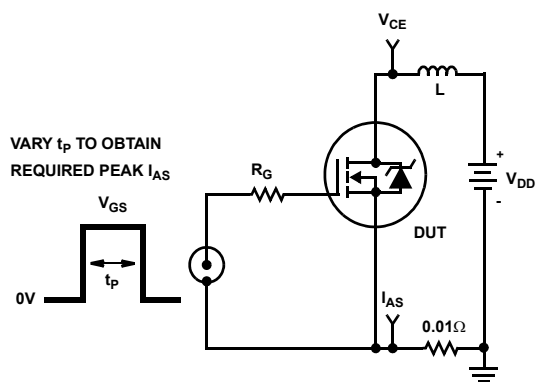


Figure 19. Energy Test Circuit

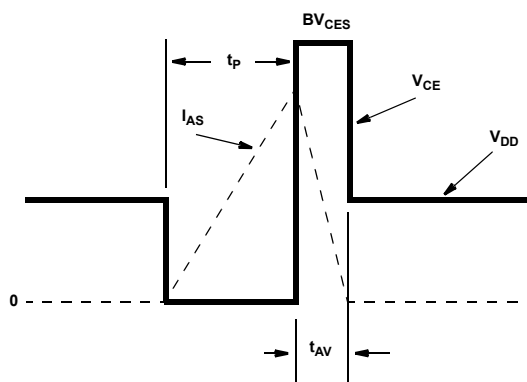


Figure 20. Energy Waveforms

## SPICE Thermal Model

REV 27 May 2005

ISL9V5045S3S / ISL9V5045S3

CTHERM1 th 6 82e-4  
CTHERM2 6 5 105e-4  
CTHERM3 5 4 12e-3  
CTHERM4 4 3 33e-3  
CTHERM5 3 2 55e-3  
CTHERM6 2 tl 170e-3

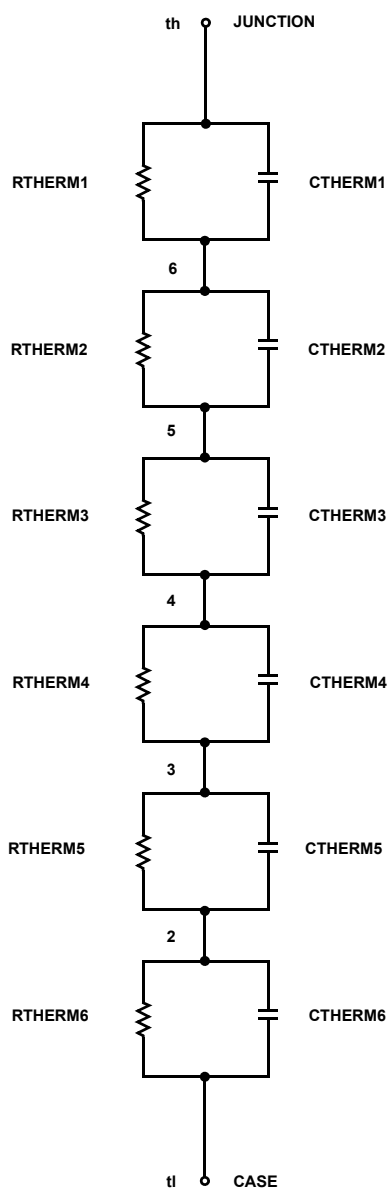
RTHERM1 th 6 3e-3  
RTHERM2 6 5 20e-3  
RTHERM3 5 4 50e-3  
RTHERM4 4 3 60e-3  
RTHERM5 3 2 100e-3  
RTHERM6 2 tl 127e-3

## SABER Thermal Model

SABER thermal model  
ISL9V5045S3S / ISL9V5045S3  
template thermal\_model th tl  
thermal\_c th, tl

```
{
  ctherm.ctherm1 th 6 = 82e-4
  ctherm.ctherm2 6 5 = 105e-4
  ctherm.ctherm3 5 4 = 12e-3
  ctherm.ctherm4 4 3 = 33e-3
  ctherm.ctherm5 3 2 = 55e-3
  ctherm.ctherm6 2 tl = 170e-3
```


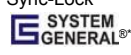



```
rtherm.rtherm1 th 6 = 3e-3
rtherm.rtherm2 6 5 = 20e-3
rtherm.rtherm3 5 4 = 50e-3
rtherm.rtherm4 4 3 = 60e-3
rtherm.rtherm5 3 2 = 100e-3
rtherm.rtherm6 2 tl = 127e-3
}
```





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